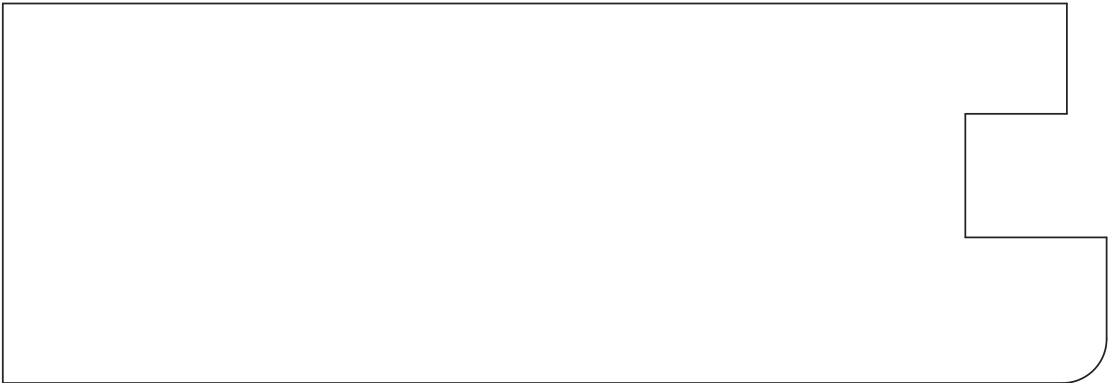


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

Z23 ■ This Assembly Note will show in the PcbDoc and associated outputs
 Z22 ■ This Assembly Note will show in the PcbDoc and associated outputs
 Z21 ■ This Assembly Note will show in the PcbDoc and associated outputs

848



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

BOARD #: TIDA-01333 REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01333

PLOT NAME = Bottom Assembly Drawing

GENERATED : 23.02.2017 09:31:44

TEXAS INSTRUMENTS

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